DESIGNING ROBUST SYSTEMS with UNCERTAIN INFORMATION

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The philosophical paradigm

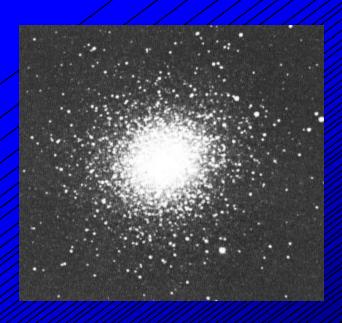
Science at the onset of the XX century

Laplacian determinism

 The future state of the universe can be determined from its present state

Quantum theory and uncertainty

We can neither observe nor control microscopic features with accuracy



The philosophical paradigm

Design technology at the onset of the XXI century

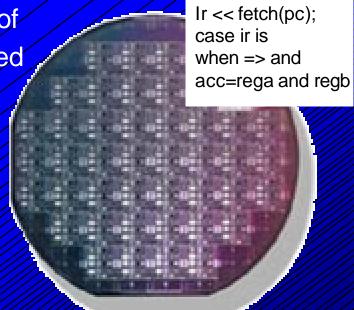
Design determinism

 The complete behavior and features of a microelectronic circuit can be derived from a hardware model

Synthesis technology

 Design uncertainty with nanoscale technologies

- Need for high-level abstractions
- Inaccuracy of low-level models



The economic perspective

- System on Chip (SoC) design:
 - Increasingly more complex:
 - Many detailed electrical problems
 - Integration of different technologies
 - Increasingly more expensive and risky
 - A mask set may cost over a million dollars
 - A single functional error can kill a product
 - Fewer design starts
- Large volume needed to recapture hw costs
 - Software solutions are more desirable

The SoC market

- SoCs find application in many embedded systems
- Concerns:



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Correctness
Reliability and safety
Robustness

Performance
Energy consumption
Cost







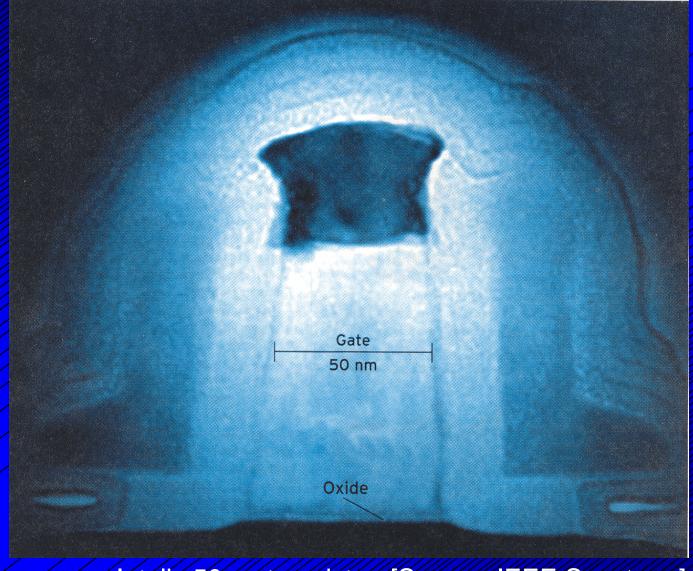
Robust design

- SoCs must preserve correct operation and performance:
 - Under varying environmental conditions
 - Under changes of design assumptions
- Designing correct and performing circuits becomes increasingly harder
 - Too many factors to take into account
- Paradigm shift needed
 - Design error-tolerant and adaptive circuits

Issues

- Extremely small size
 - Coping with deep submicron (DSM) technologies
 - Spreading of parameters
- Extremely large scale
 - System complexity
 - Changing environmental conditions
- New fabrication materials
 - Novel technologies
 - How to make the leap

Extremely small size



Intel's 50nm transister Source: IEEE Spectrum]

Silicon technology roadmap

Year	Gate length (<i>nm</i>)	Transistor density (<i>million/cm</i> ²)	Clock rate (<i>GHz</i>)	Supply voltage (V)
2002	75	48	2.3	
2007	35	154	6.7	0.7
2013	13	617	19.3	0.5

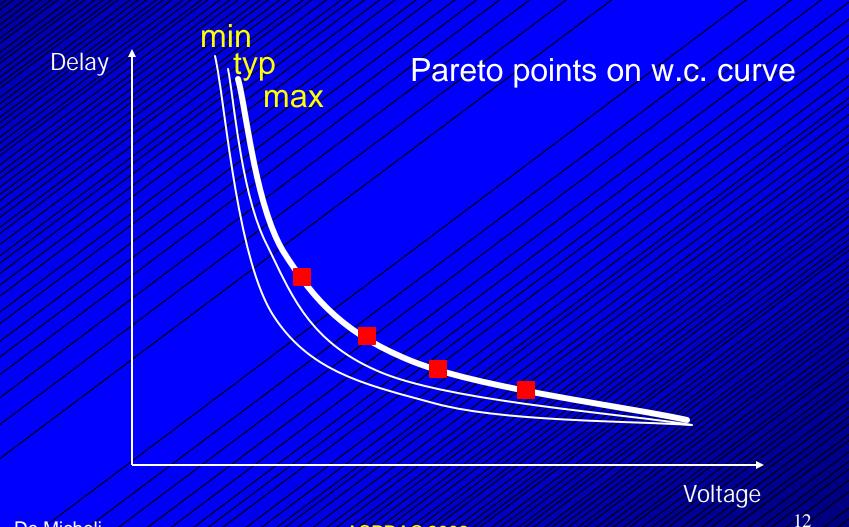
Qualitative trends

- Continued gate downscaling
- Increased transistor density and frequency
 - Power and thermal management
- Lower supply voltage
 - Reduced noise immunity
- Increased spread of physical parameters
 - Inaccurate modeling of physical behavior

Critical design issue

- Achieve desired performance levels with limited energy consumption
- Dynamic power management (DPM)
 - Component shut off
 - Frequency and voltage downscaling
- Éxplore (at run time) the voltage/delay trade off curve

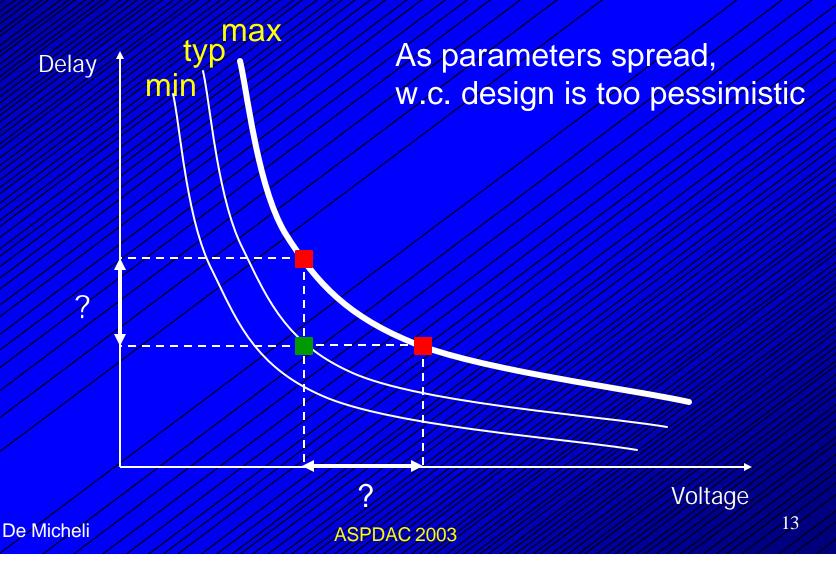
Design space exploration worst case analysis



ASPDAC 2003

De Micheli





Self-calibrating circuits

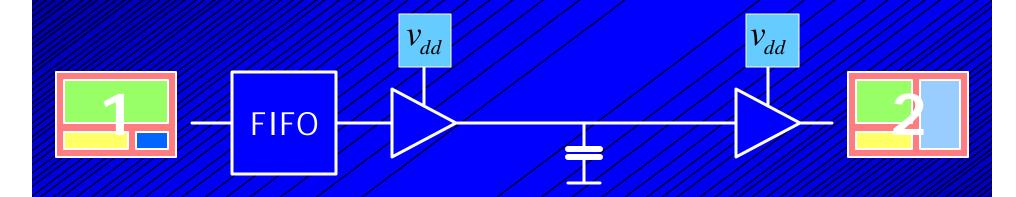
- The operating points of a circuit should be determined on-line
 - Variation from chip to chip
 - Operation at the edge of failure
- Analogy
 - Sailing boat tacking against the wind
 - Max gain when sailing close to wind
 - When angle is too close, large loss of speed



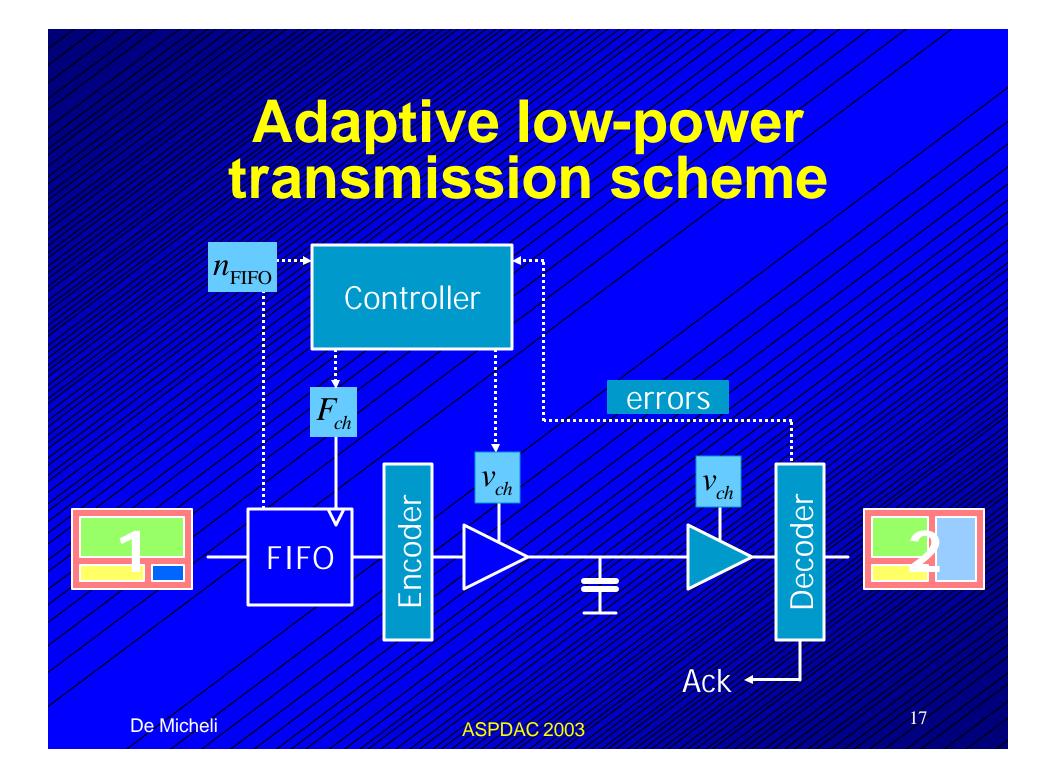
How to calibrate?

- General paradigm
 - A circuit may be in correct or faulty operational state, depending on a parameter (e.g., voltage)
 - Computed/transmitted data need checks
 - If data is faulty, data is recomputed and/or retransmitted
 - Error rate is monitored on line
 - Feedback loop to control operational state parameter based on error rate
- Circuits can generate errors:
 - Errors must be detected and corrected
 - Correction rate is used for calibration





- Globally asynchronous, locally synchronous (GALS)
- FIFO for decoupling
- Variable transmission frequency



Self-calibration

- Self-calibration makes circuit robust against:
 - Design process variations
 - External disturbances
 - E.g., soft errors, EM interference, environment
- Self-calibration may take different embodyments
 - May be applied during normal operation
 - To compensate for environmental changes
 - May be used at circuit boot time
 - To compensate for manufacturing variations
- General paradigm to cope with DSM problems

Extremely large scale

- Engineers will always attempt to design chips at the edge of human capacity
- Challenges:
 - Large scale: billion transistor chips
 - Heterogeneity: digital, analog, RF, optical, MEMS, sensors, micro-fluidics
- Many desiderata: high performance, low power, low cost, fast design, small team, ...

Component-based design

- SoCs are designed (re)-using large macrocells
 - Processors, controllers, memories...
 - Plug and play methodology is very desirable
 - Components are qualified before use
- Design goal:
 - Provide a functionally-correct, reliable operation of the interconnected components
- Critical issues:
 - Properties of the physical interconnect
 - Achieving robust system-level assembly

Physical interconnection

- Electrical-level information transfer is unreliable
 - Timing errors
 - Delay on global wires and delay uncertainty
 - Synchronization failure across different islands
 - Crosstalk-induced timing errors
 - Data errors:
 - Data upsets due to EM interference and soft errors
- Noise is the abstraction of the error sources
- The problem will get more and more acute as geometries and voltages scale down

Systems on chips: a communication-centric view

- Design component interconnection under:
 - Uncertain knowledge of physical medium
 - Incomplete knowledge of environment
 - Workload, data traffic, ...
- Design interconnection as a micro-network
 - Leverage network design technology
 - Manage information flow
 - To provide for performance
 - Power-manage components based on activity
 - To reduce energy consumption

Micro-network characteristics

- Micro-networks require:
 - Low communication latency
 - Low communication energy consumption
 - Limited adherence to standards
- SoCs have some physical parameters that:
 - Can be predicted accurately
 - Can be described by stochastic distributions

Micro-network stack

Software

- application
- •system

Architecture and control

- •transport
- network
- data link

Physical •wiring

Design choices at each stack level affect:

- Communication speed
- Reliability
- Energy

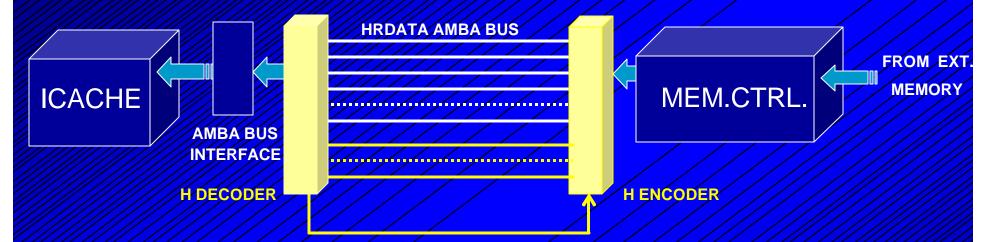
Control Protocols:

- Layered
- Implemented in Hw or Sw
- Providing error correction

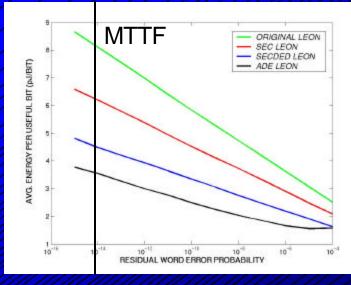
Achieving robustness in micro-networks

- Error detection and correction is applied at various layers in micro-networks
- Paradigm shift:
 - Present design methods reduce noise
 - Physical design (e.g., sizing, routing)
 - Future methods must cope with noise
 - Push solution to higher abstraction levels

Data-link protocol example: error-resilient coding



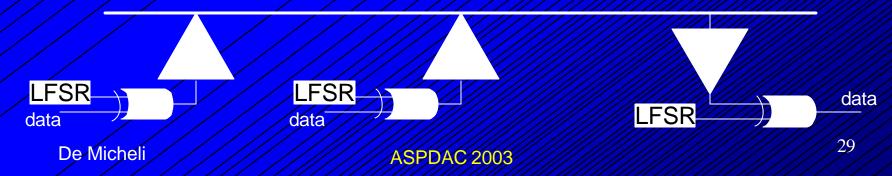
- Compare original AMBA bus to extended bus with error detection and correction or retransmission
 - SEC coding
 - SEC-DED coding
 - ED coding
- Explore energy efficiency



28

Advanced bus techniques: CDMA on bus

- Motivation: many data sources
 - Support multiple concurrent write on bus
 - Discriminate against background noise
- Spread spectrum of information
 - Driver/receiver multiply data by random sequence generated by LFSR
 - LFSR signature is key for de-spreading



Going beyond buses

- Buses:
 - Pro: simple, existing standards
 - Contra: performance, energy-efficiency, arbitration
- Other network topologies:
 - Pro: higher performance, experience with MP
 - Contra: physical routing, need for network and transport layers
- Challenge: exploit appropriate network architecture and corresponding protocols

Network and transport layers

- Information is in packets
- Network issues:
 - Network switching
 - Circuit, packet, cut-through, wormhole
 - Network routing
 - Deterministic and adaptive routing
- Transport issues:
 - Decompose and reconstruct information
 - Packet granularity
 - Admission/congestion control

SPIN micro-network

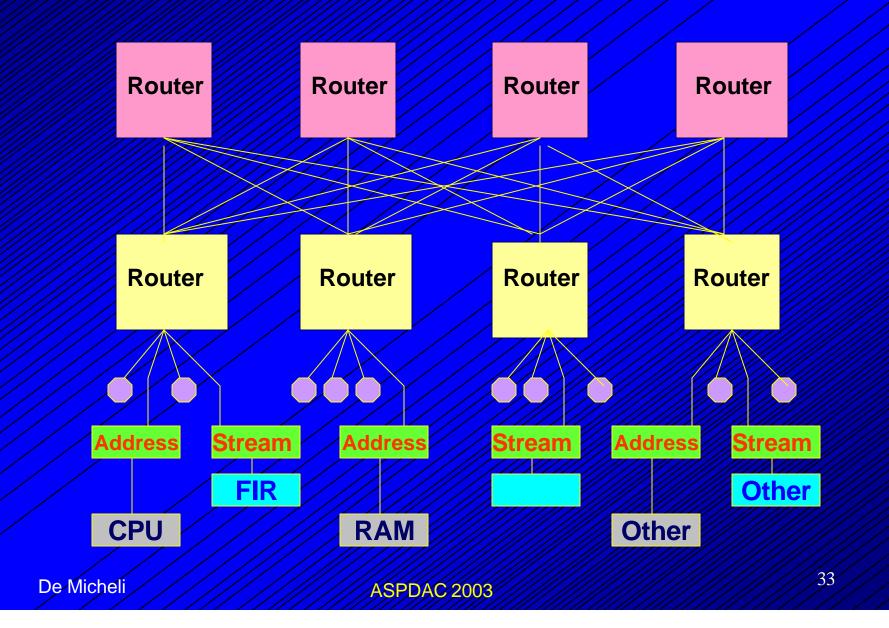
- Applied to SoCs
- 36-bit packets
 - Header: destination
 - -Trailer: checksum



- Fat-tree network architecture
- Cut-through switching
- Deterministic tree routing

Address

SPIN micro-network



Benefits of packets

- Reliable error-control mechanism
 - With small overhead
- Exploit different routing paths
 - Spread information to avoid congestion
- Several user-controllable parameters
 - Size, retransmission schemes, ...
- Use retransmission rate for calibrating parameters

System assembly around micro-network

- Network architecture provides backbone
- Component plug and play:
 - Programmable network interface
 - Reconfigurable protocols
 - Recognize network and self configure
- Self-assembly of SoCs addresses the issue of component reuse and heterogeneity

Extremely large scale design

- Heterogeneous components with malleable interfaces
- Macroscopic self-assembly
 - Exploit degrees of freedom in component/interface specifications
 - Self-configuration realizes interfacing details abstracted by designers
 - Self-configuration, together with redundancy, addresses selfcorrection of some possible design errors

Self-healing

- Correcting for run-time failures
- Method to increase availability and robustness

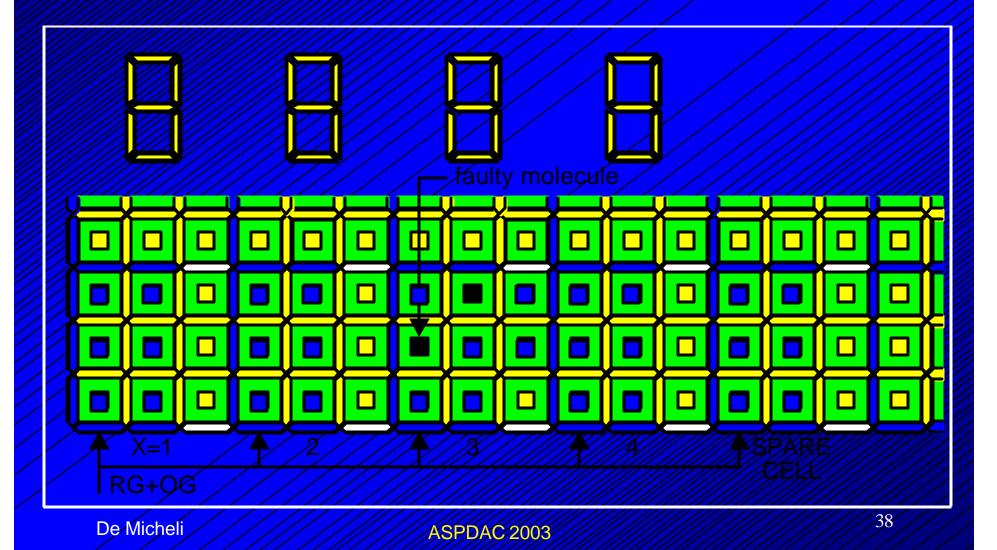
Example: Biowall

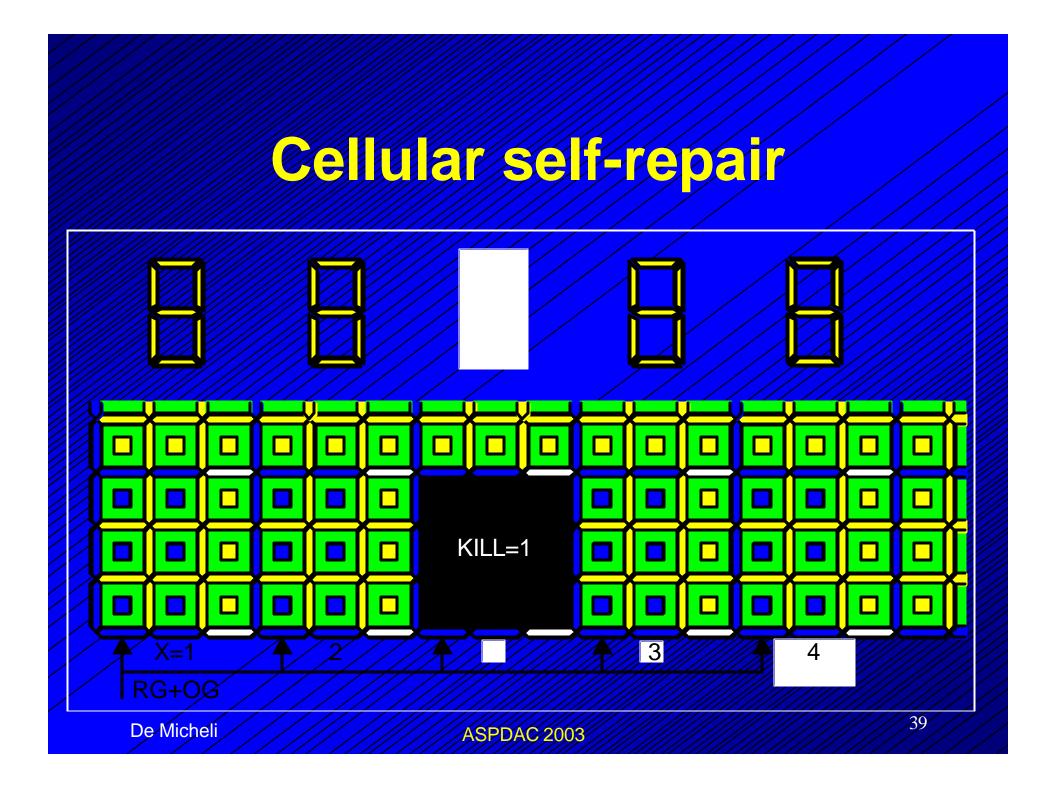


- Embryonics project at EPFL, Switzerland
- Cellular design with redundancy
 - Each cell programmed by a string (gene)
 - FPGA technology
- Self-healing property:
 - Upon cell failure, neighbors reconfigure to take over function

37







Autonomic computing

- Broad R&D project launched by IBM
- Self-healing
 - Design computer and software that perform self-diagnostic functions and can fix themselves without human intervention
 - Strong analogies to biological systems
- Reduced cost of design and maintenance

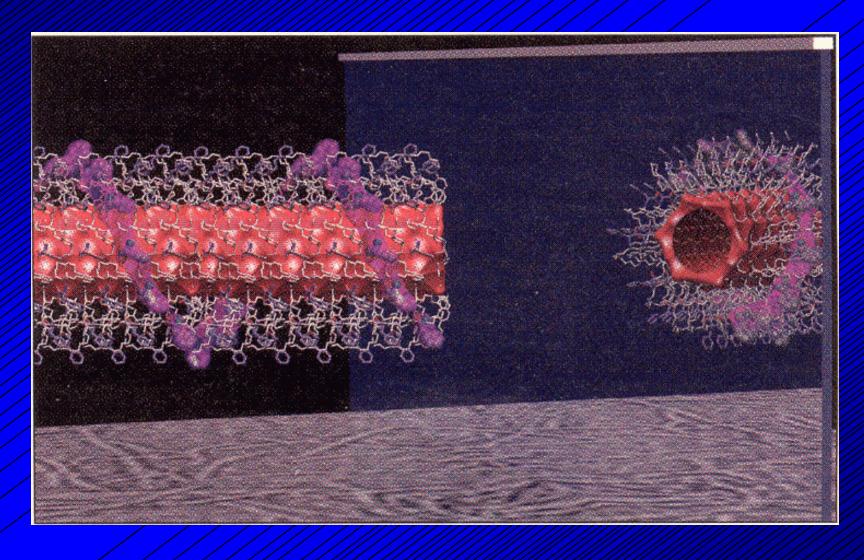
Autonomics principles

- An autonomic system:
 - must know itself
 - reconfigures itself under varying condition
 - optimizes its operations at run time
 - must support self-healing
 - must defend itself against attacks
 - must know the environment
 - manages and optimizes internal resources without human intervention

Evolving computing materials

- When will current semiconductor technologies run out of steam?
- What factor will provide a radical change in technology?
 - Performance, power density, cost?
- Several emerging technologies:
 - Carbon nanotubes, nanowires, quantum devices, molecular electronics, biological computing, ...
- Are these technologies compatible with silicon?
 - What is the transition path?
- What are the common characteristics, from a design technology standpoint?

Rosette nanotubes



Common characteristics of nano-devices

- Self-assembly used to create structures
 - Manufacturing paradigm is bottom-up
- Significant presence of physical defects
 - Design style must be massively fault-tolerant
- Competitive advantage stems from extreme high density of computing elements
 - 10¹¹-10¹² dev/cm² vs. 3x10⁹ dev/cm² for CMOS in 2016
- Some nano-array technologies are compatible with silicon technology and can be embedded in CMOS

Robust nano-design

- Key ingredients:
 - Massive parallelism and redundancy
 - Exploit properties of crosspoint architectures
 - É.g., Programmable Logic Arrays (PLAs)
 - Local and global reconfiguration
- Some design technologies for robust DSM CMOS design can be applied to nanotechnology

Summary problem analysis

- The electronic market is driven by embedded applications where reliability and robustness are key figures of merit
- System design has to cope with uncertainty
 - Lack of knowledge of details, due to abstraction
 - Physical properties of the material
- As design size scales up, the design challenge is related to interconnecting high-level components
- As technology scales down, and as nanotechnologies are introduced, electrical-level information becomes unreliable

Summary design strategies

- Robust and reliable design is achieved by:
 - Self-calibrating system components
 - Networking components on chip with adaptive interfaces
 - Encoding, packet switching and routing provide a new view of logic and interconnect design
 - Self-healing components that can diagnose failures and reconfigure themselves
- New emerging technologies will require massive use of error correction and redundancy

